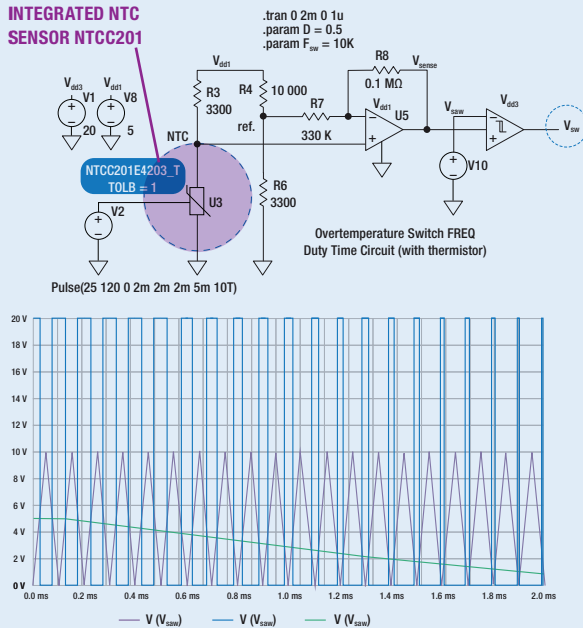




ENHANCED WIRE BONDABLE NTC DIE DESIGNED FOR IGBT MODULE TEMPERATURE PROTECTION

IGBT GATE DRIVER TEMPERATURE SHUTDOWN

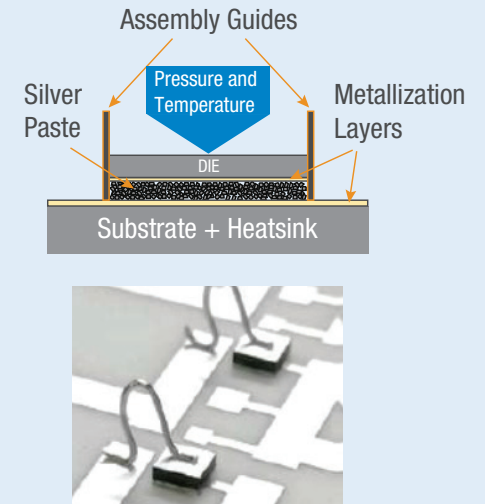


DESIGNED WITH ROBUST METALLIZATION

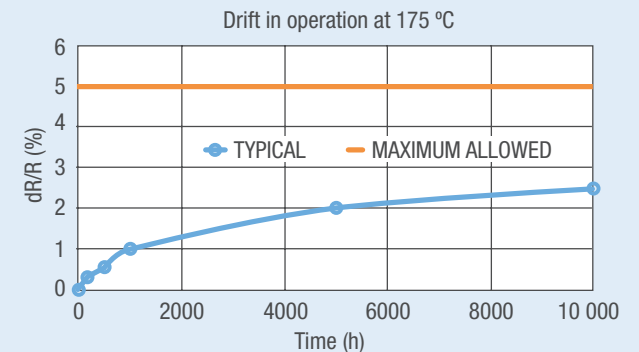
- Thick electrode
- Solderable SAC / HMP
- Resistant to flux-free soldering with formic acid



SUITABLE FOR WIRE BONDING AND NANO SILVER PASTE SINTERING



ACCURATE / STABLE AT HIGH TEMPERATURE (175 °C)



INDUSTRIES

- Power modules for EVs and hybrid vehicles
- Buck-boost DC/DC converters
- Inverters for windmills and solar panels



For technical questions: nlr@vishay.com